# Piotr Mackowiak

List of Publications by Year
in descending order



| 11 | 51 | 1684188 5 | 1720034 7 |
|---|---|---|---|
| papers | citations | h-index | g-index |

| 11 | 11 | 11 | 44 |
|---|---|---|---|
| all docs | docs citations | times ranked | citing authors |

| # | Article | IF | Citations |
|---|---|---|---|
| 1 | Design and Application of a High-G Piezoresistive Acceleration Sensor for High-Impact Application. Micromachines, 2018, 9, 266. | 2.9 | 11 |
| 2 | Development and Characterization of a Novel Low-Cost Water-Level and Water Quality Monitoring Sensor by Using Enhanced Screen Printing Technology with PEDOT:PSS. Micromachines, 2020, 11, 474. | 2.9 | 9 |
| 3 | A Novel Low Cost Wireless Incontinence Sensor System (Screen-Printed Flexible Sensor System) for Wireless Urine Detection in Incontinence Materials. Proceedings (mdpi), 2018, 2, . | 0.2 | 6 |
| 4 | Electrical Characterization of Low Temperature PECVD Oxides for TSV Applications. International Symposium on Microelectronics, 2018, 2018, 000728-000733. | 0.0 | 5 |
| 5 | Investigation and Modeling of Etching Through Silicon Carbide Vias (TSiCV) for SiC Interposer and Deep SiC Etching for Harsh Environment MEMS by DoE. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 437-445. | 2.5 | 5 |
| 6 | Development and fabrication of a very High-g sensor for very high impact applications. Journal of Physics: Conference Series, 2016, 757, 012016. | 0.4 | 4 |
| 7 | Fabrication of High Voltage Capable TSV Using Backside via Last Process and Laser Abblation of Dry Film BCB. , 2019, , . | | 4 |
| 8 | A WSiâ€“WSiNâ€“Pt Metallization Scheme for Silicon Carbide-Based High Temperature Microsystems. Micromachines, 2016, 7, 193. | 2.9 | 3 |
| 9 | Investigation of Etching SIC VIAS for High Power Elctronics and Harsh Enviornment Mems. , 2020, , . | | 3 |
| 10 | Evaluation and Signal Conditioning of Piezoresistive Silicon Pressure Sensor. Applied Mechanics and Materials, 2014, 530-531, 28-32. | 0.2 | 1 |
| 11 | Wireless Pressure Sensor System. Applied Mechanics and Materials, 2014, 530-531, 75-78. | 0.2 | 0 |